

## APPROVAL SHEET

Approval Specification	Customer's Approval Certificate
TO:	Please return this copy as a certification of your approval
Part No.:	Checked & Approved by:
Customer's Part No.:	Date:

# BEIJING ZHONGXUN SIFANG SCIENCE & TECHNOLOGY CO.,LTD.

Tel: +86-010-58937383
Fax: +86-010-58937263
E-mail: bjzxsf@bjzxsf.net
Website: http://www.bjzxsf.net

Add: No 201, Block A. Building 3. Yongjie Beilu

Yongfeng high-tech industrial base Haidian District Beijing city

Part No.	:	SF1467
Pages	:	6
Date	:	2015/1/20
Revision	:	1.0



Prepared by:	梁浩
Checked by:	gly g
Approved by:	3622

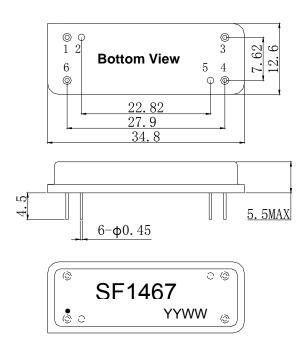
#### **Application**

- High-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Passband 3.4 MHz
- Low Shape factor

#### **Features**

- RoHS compatible
- Package size 34.8x12.6x5.50mm³
- Package Code DIP3512
- Electrostatic Sensitive Device(ESD)

#### Package Dimensions (Unit: mm)



### Pin Configuration

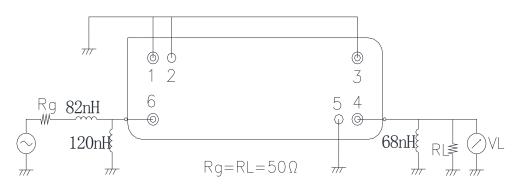
Pin No.	Description		
6	Input		
4	Output		
1,2,3,5	Ground		

#### **Marking Description**

S	Trademark	
F	SAW Filter	
1467	Part Number	
•	Pin 1	
YYWW	Year Code & Week Code	

\*Fig: If the products produced in 06<sup>th</sup> week of 2012, The year code & week code is 1206.

#### **Test Circuit(Bottom View)**



Please read notes at the end of this document.

- 2 -

www.bjzxsf.net

2015/1/20

#### **Performance**

#### **Maximum Rating**

Item		Value	Unit
DC Voltage	V <sub>DC</sub>	3	V
Operation Temperature	Т	-40 ~ +85	$^{\circ}$
Storage Temperature	T <sub>stg</sub>	-55 ~ +125	$^{\circ}\!\mathbb{C}$
RF Power Dissipation	Р	10	dBm

#### **Electronic Characteristics**

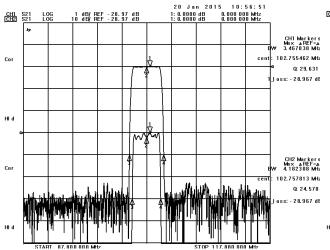
Test Temperature:  $25^{\circ}C \pm 2^{\circ}C$ 

Terminating source impedance:  $50\Omega$ Terminating load impedance:  $50\Omega$ 

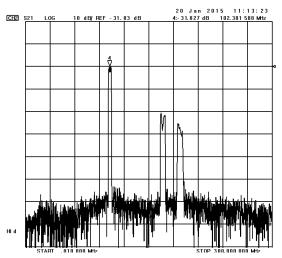
Item		Minimum	Typical	Maximum	Unit
Center Frequency	fc		102.8		MHz
Insertion Loss(min)	IL		29.0	30.0	dB
Amplitude Ripple	∆a		0.5	1.5	dB
1.5 dB Bandwidth	BW <sub>1.5dB</sub>		3.32		MHz
3 dB Bandwidth	BW <sub>3dB</sub>	3.40	3.46		MHz
30 dB Bandwidth	BW <sub>30dB</sub>		4.1	4.2	MHz
45 dB Bandwidth	BW <sub>45dB</sub>		4.2	4.6	MHz
Absolute Delay	AD		3.6	4.0	us
Absolute Attenuation	а	50.0	51.0		dB

#### **Frequency Characteristics**

#### Frequency Response



#### Frequency Response (wideband)

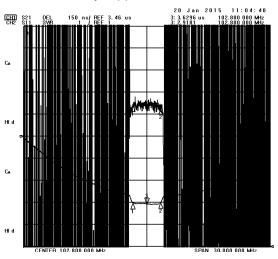


CH2 Markers Ma× 1:-94.183 dE 70.0000 MH2

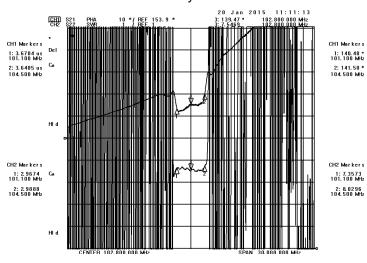
2:- 92.768 dE 110.000 MHz

3:- 96, 083 dE 150, 000 MHz

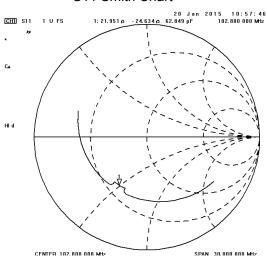
#### Delay Ripple & S11 VSWR



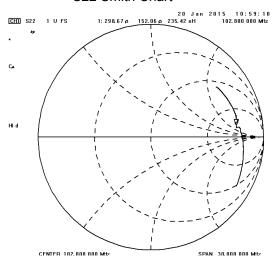
#### Phase Linearity & S22 VSWR



#### S11 Smith Chart



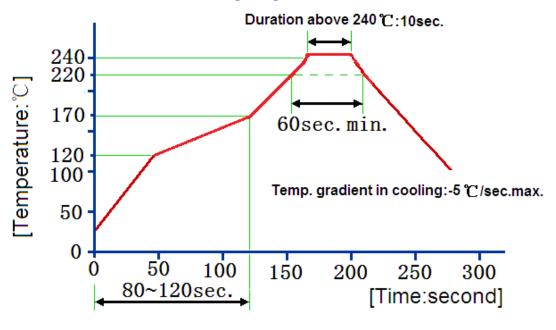
S22 Smith Chart



#### Reliability (The SAW components shall remain electrical performance after tests)

No.	Test item	Test condition		
4	Temperature	(1) Temperature: 85℃±2℃, Duration: 250h, Recovery time: 2h±0.5h		
ļ	Storage	(2) Temperature: −55°C±3°C , Duration: 250h ,Recovery time: 2h±0.5h		
2	Humidity Test	Conditions: 60℃±2℃ , 90~95% RH		
3	0 7 10 1	Heat cycle conditions: TA=-55℃±3℃, TB=85℃±2℃, t1=t2=30min, Switch		
3	Thermal Shock	time: ≤3min, Cycle time: 100 times, Recovery time: 2h±0.5h.		
1	4 Vibration Fatigue	Frequency of vibration: 10~55Hz Amplitude:1.5mm		
_		Directions: X,Y and Z Duration: 2h		
5	Drop Test	Cycle time: 10 times Height: 1.0m		
		Temperature: 245 ℃ ±5 ℃ Duration: 3.0s5.0s		
6	Solder Ability Test	Depth: DIP2/3 , SMD1/5		
		(1)Thickness of PCB:1mm , Solder condition: 260 ℃±5 ℃ , Duration: 10±1s		
7	Resistance to Soldering Heat	(2)Temperature of Soldering Iron: 350 ℃±10 ℃,Duration: 3~4s,		
		Recovery time: 2 ± 0.5h		

#### **Recommended Reflow Soldering Diagram**



Reflow cycles:3 cycles max.

102.80MHz SAW Filter SF1467 3.40 MHz Bandwidth

#### **Notes**

- 1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
- 2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
- 3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
- 4. Only leads of component may be soldered. Please avoid soldering another part of component.
- 5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.

Please read notes at the end of this document.